

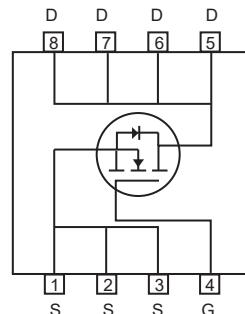
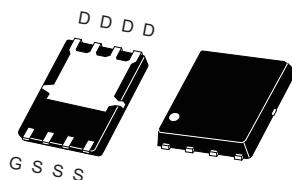


# CEZ06R10SLA

## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 100V, 66A,  $R_{DS(ON)} = 7.5\text{m}\Omega$  @ $V_{GS} = 10\text{V}$ .  
 $R_{DS(ON)} = 11\text{m}\Omega$  @ $V_{GS} = 4.5\text{V}$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- Surface mount Package.



P-PAK 5X6

### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D @ R_{QJC}$	66	A
Drain Current-Continuous	$I_D @ R_{QJA}$	21	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM} @ R_{QJC}$	264	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM} @ R_{QJA}$	84	A
Maximum Power Dissipation	$P_D$	59.5	W
Single Pulsed Avalanche Energy <sup>d</sup>	$E_{AS}$	60.5	mJ
Single Pulsed Avalanche Current <sup>d</sup>	$I_{AS}$	11	A
Operating and Store Temperature Range	$T_J, T_{Stg}$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{QJC}$	2.1	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{QJA}$	20	$^\circ\text{C/W}$



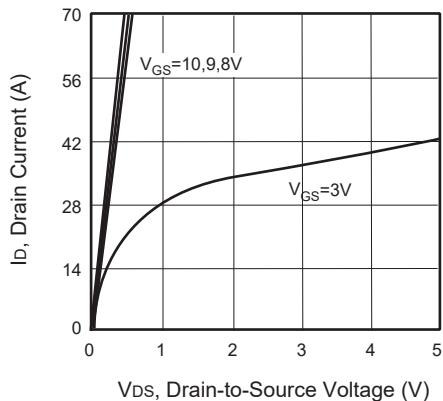
# CEZ06R10SLA

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

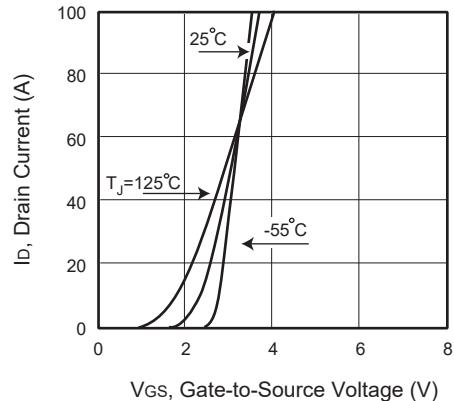
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 30\text{A}$		6.0	7.5	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 20\text{A}$		8.3	11	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		2240		pF
Output Capacitance	$C_{\text{oss}}$			420		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			25		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 80\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		21		ns
Turn-On Rise Time	$t_r$			4		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			61		ns
Turn-Off Fall Time	$t_f$			14		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 80\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 4.5\text{V}$		23		nC
Gate-Source Charge	$Q_{\text{gs}}$			4		nC
Gate-Drain Charge	$Q_{\text{gd}}$			17		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				49	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 1\text{A}$			1.2	V

Notes :

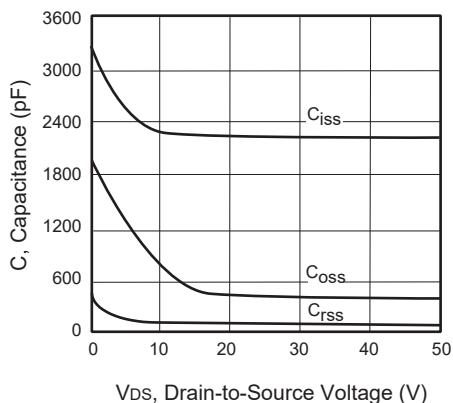
- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ . Duty Cycle  $\leq 2\%$ .
- c.Guaranteed by design, not subject to production testing.



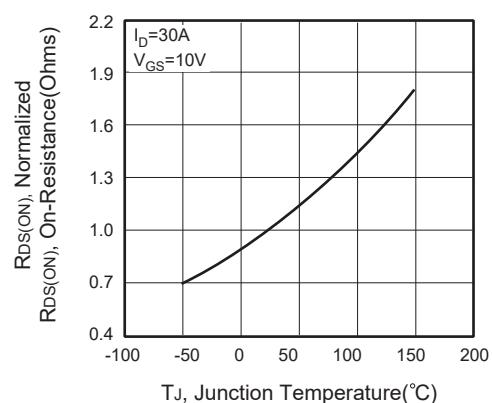
**Figure 1. Output Characteristics**



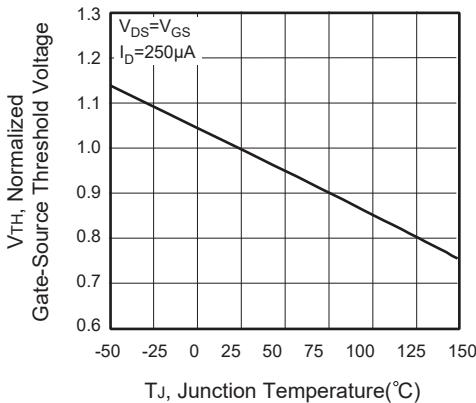
**Figure 2. Transfer Characteristics**



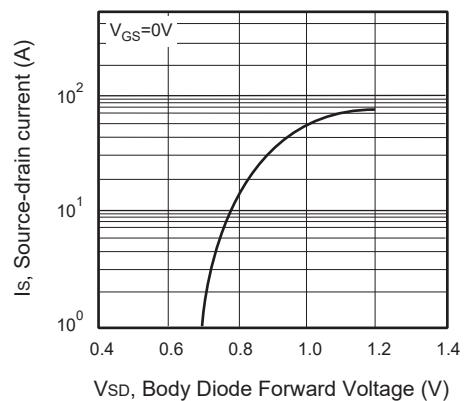
**Figure 3. Capacitance**



**Figure 4. On-Resistance Variation with Temperature**



**Figure 5. Gate Threshold Variation with Temperature**



**Figure 6. Body Diode Forward Voltage Variation with Source Current**

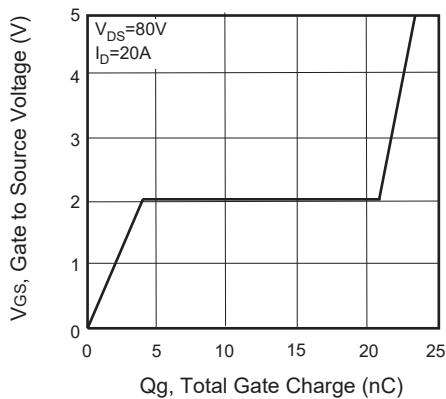


Figure 7. Gate Charge

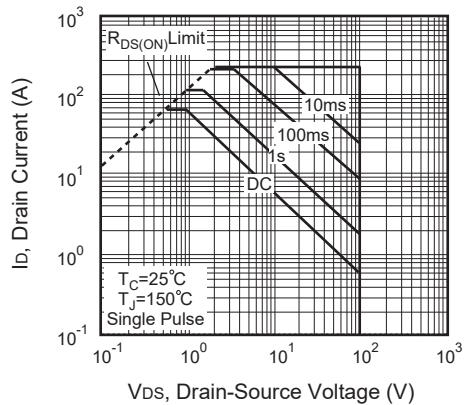


Figure 8. Maximum Safe  
Operating Area

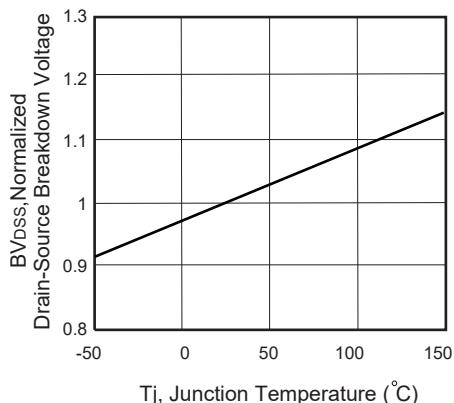


Figure 9. Breakdown Voltage Variation  
VS Temperature

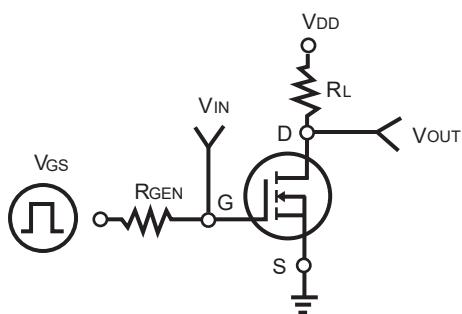


Figure 10. Switching Test Circuit

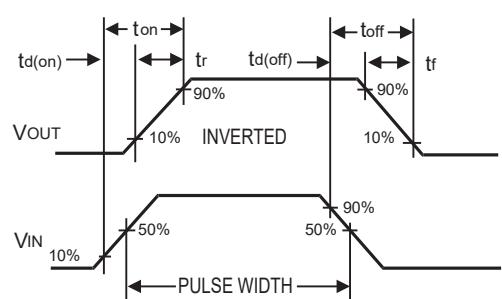


Figure 11. Switching Waveforms

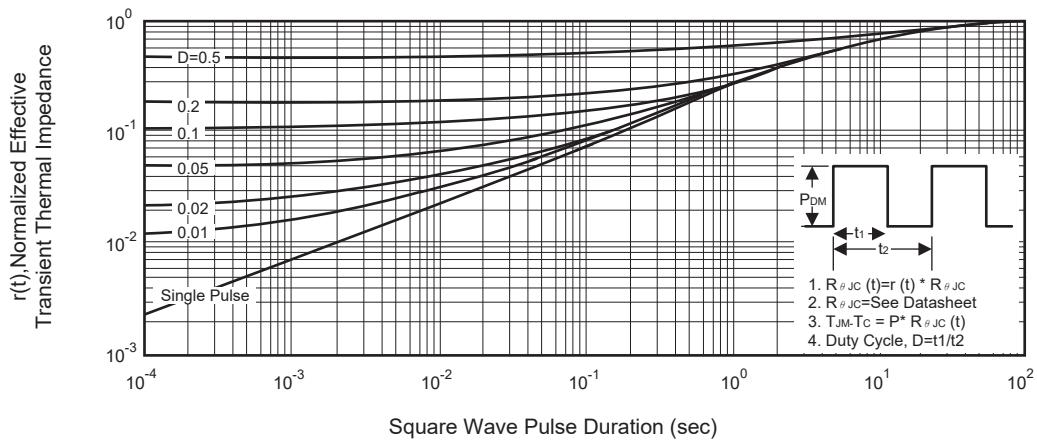


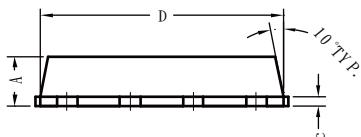
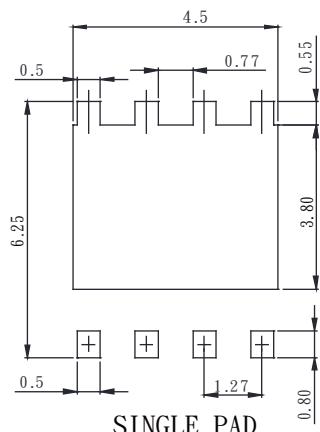
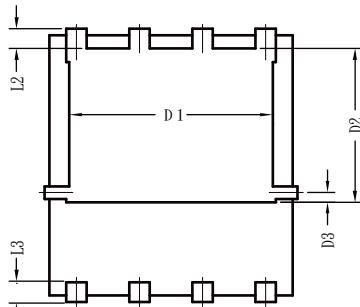
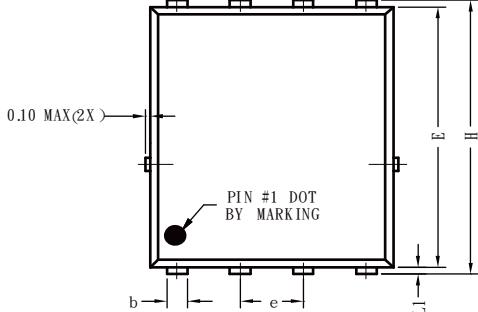
Figure 12. Normalized Thermal Transient Impedance Curve



# CEZ06R10SLA

P-PAK5X6 產品外觀尺寸圖 (Product Outline Dimension)

## SINGLE PAD 尺寸圖



RECOMMENDED LAND PATTERN

SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.800	1.170	0.031	0.046
b	0.340	0.490	0.013	0.019
c	0.20	0.34	0.008	0.013
D	4.800	5.100	0.009	0.011
D1	3.800	4.200	0.150	0.165
D2	3.180	3.78	0.125	0.149
D3	0.150	0.360	0.006	0.142
E	5.650	5.900	0.222	0.232
e	1.270 TYP		0.050 TYP	
H	5.900	6.150	0.232	0.242
L1	0.050	0.250	0.002	0.010
L2	0.380	0.620	0.015	0.024
L3	0.380	0.75	0.015	0.030